

AMENDMENTS TO THE CLAIMS:

Please amend the claims as follows:

1. (Currently amended) A method for producing conductive particles comprising the steps of:

introducing a solution composed mainly of palladium chloride and hydrochloric acid into an electroless plating bath containing a reducing agent, and one from the group consisting of particles of an organic material or particles of an inorganic material while stirring said bath; and

simultaneously applying an electroless plating to the surface of said particles and allowing the palladium catalyst to be carried on the surface of said particles to give conductive particles having an electroless plate coating,

wherein said electroless plate coating comprises at least one selected from the group consisting of Ni, Ni-P, Ni-B, Cu, an Ni-PTFE composite coating and a Cu-PTFE composite coating, and

wherein said electroless plate coating has three-dimensionally connected pores that allow water molecules, hydroxy ions, sodium ions or potassium ions to pass through and diffuse.

2. (Original) The method for producing conductive particles in accordance with claim 1, wherein said solution has a palladium chloride concentration of 0.3 to 10 g/L.

3. (Cancelled)

4. (Original) The method for producing conductive particles in accordance with claim 1, wherein said inorganic material comprises at least one selected from the group consisting of Cu, Ni, Al, Fe, Ag, Mo and W or any alloy thereof.

5. (Original) The method for producing conductive particles in accordance with claim 1, wherein said inorganic material comprises at least one selected from the group consisting of Al₂O₃, SiO₂, Ni(OH)₂ and Ca(OH)₂.

6. (Cancelled)